

**Amendments to the Specification:**

At page 3, line 5, before the paragraph that begins "Figure 2 is . . .," please insert the following new paragraph:

Figure 1b is a schematic illustration of two of the "I-beam" modules of Figure 1 side by side.

At page 5, line 6, before the section titled "Detailed Description of the Preferred Embodiments," please insert the following new paragraphs:

Figure 34 is a fragmented cross sectional view as would be shown taken along lines XXXIV – XXXIV in Figure 14 when the plug and receptacle elements of the connector are engaged.

Figure 35 is a fragmented cross sectional view as would be shown taken along lines XXXV – XXXV in Figure 32 when the plug and receptacle elements of the connector are engaged.

Please replace the paragraph beginning at page 5, line 24 and ending at page 6, line 5, with the following amended paragraph:

Taking an equipotential line close to one of the ground planes and following it out towards the boundaries A and B, it will be seen that both boundary A or boundary B are very close to the ground potential. This means that at both boundary A and boundary B we have virtual ground surfaces and if two or more I-beam modules are placed side by side, as illustrated in Figure 1b, a virtual ground surface exists between the modules and there will be no coupling between the modules. In general, the conductor width  $w_c$  and dielectric thickness should be small compared to the dielectric width or module pitch.

Please replace the paragraph beginning at page 10, line 10 and ending at page 10, line 16, with the following amended paragraph:

Referring particularly to Figures 14 and 15, the plug and receptacle are shown respectively in a disengaged and in an engaged configuration. It will be observed that the major forward extension 146 of the dielectric section of the plug abuts the minor forward extension 146 of the dielectric section of the receptacle end to end. The major forward extension of the dielectric section of the receptacle abuts the minor forward extension of the dielectric section of the plug end to end. Figure 34, a fragmented cross sectional view as would be shown taken along lines XXXIV – XXXIV in Figure 14 when the plug and receptacle elements of the connector are engaged, reveals the resulting I-beam geometry.

Please replace the paragraph beginning at page 14, line 19 and ending at page 15, line 2 (which was previously replaced via the Preliminary Amendment filed August 10, 2001) with the following further amended paragraph:

Referring to Figures 28-31, a receptacle which mates with the plug 420 is shown generally at numeral 456. This receptacle includes a base section dielectric 458, a peripheral beveled edge 460 and rows of metallic pin receiving recesses as at 462, 464, 466, 468 and 470. Metallic grounding or power elements receiving structures 472, 474, 476, 478, 480 and 482 are interposed between the rows of pin receiving recesses. On its bottom, or mounting, side the receptacle also includes alignment and mounting pins 484 and 486 which enter corresponding openings (not shown) in a substrate (not shown) during mounting. Further, the bottom side of the receptacle includes rows of solder conductive pads to which solder masses, such as the solder balls

488 and 490 shown in Figure 30, secure (*i.e.*, are fused). As seen in Figure 33, the solder conductive pad of contact 470 is an angled portion 456 which resides in a recess 459 in the base. As customary in ball grid array assemblies, solder balls 488, 490, once reflowed, secure receptacle 456 to a substrate (not shown). From Figures 32-33 and Figure 35, which is a fragmented cross sectional view as would be shown taken along lines XXXV – XXXV in Figure 32 when the plug and receptacle elements of the connector are engaged, it will be observed that the same I-beam geometry as was described above is available with this arrangement.